Amendments to the Claims

This listing of claims will replace all prior listings of claims in the application.

Listing of Claims

1.-10. (Canceled)

11. (New) A method for manufacturing a multi-layer ceramic electronic part comprising the steps of:

 $\sqrt{\text{preparing an unbaked laminated body comprising a}}$ ceramic layer and internal electrodes laminated on one another;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body by applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body; and

baking the unbaked laminated body and the external electrodes simultaneously to sinter them.

 $\sqrt{12}$. (New) A method for manufacturing a multi-layer ceramic electronic part comprising the steps of:

 $\sqrt{}$ preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another:

applying and drying a conductor paste, into which is added a_material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body; baking the laminated body; and



providing ceramic portions which are scattered in a conductor film forming the external electrodes and continuous in a direction of thickness of the conductor film.

13. (New) A method for manufacturing a multi-layer ceramic electronic part comprising the steps of:

preparing an unbaked laminated body comprising a ceramic layer and internal electrodes laminated on one another;

applying and drying a conductor paste, into which is added a material common with a ceramic forming the ceramic layer of the laminated body, on edge portions of the unbaked laminated body;

forming external electrodes in contact with the internal electrodes at end surfaces of the laminated body;

baking the laminated body; and

forming ceramic portions in the external electrodes that are continuous from an inner surface of a conductor film forming the external electrodes where the conductor film closely contacts with a surface of the laminated body, extending to an outer surface of the external electrodes.

- $\sqrt{\ 14.}$ (New) The method of Claim 11, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.
- 15. (New) The method of Claim 12, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.
- 16. (New) The method of Claim 13, additionally comprising the step of forming the conductor film of at least one metal selected from the group consisting of Ni, Cu, Ag, Pd and an Ag-Pd alloy.

20

- 17. (New) The method of Claim 11, wherein the ceramic comprises barium titanate.
- 18. (New) The method of Claim 12, wherein the ceramic comprises barium titanate.
- 19. (New) The method of Claim 13, wherein the ceramic comprises barium titanate.
- 63
- 20. (New) The method of Claim 11, wherein the conductor paste contains from 3-40 wt.% of the common material. 7
- 21. (New) The method of Claim 12, wherein the conductor paste contains from 3--40 wt.% of the common material.
- 22. (New) The method of Claim 13, wherein the conductor paste contains from 3-40 wt.% of the common material.